

<b>Notification Number:</b>	<b>20181214001</b>	<b>Notification Date:</b>	Dec 17, 2018
<b>Title:</b>	Datasheet update for MSP430F5xx		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

<b>Notification Details</b>										
<b>Description of Change:</b>										
<p>Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.</p> <p>Review DS revision history for the detailed change description. Various changes have been made to each of the datasheets listed below. The change to the PMM BORH, COMP_B tEN, and DSBGA dimension information is most significant from the list of changes included in the datasheet revision histories.</p> <p>The datasheet number will be changing.</p> <table border="1"> <thead> <tr> <th>Device Family</th> <th>Change From:</th> <th>Change To:</th> </tr> </thead> <tbody> <tr> <td><a href="#">MSP430F522x</a>, <a href="#">MSP430F521x</a></td> <td>SLAS718G</td> <td>SLAS718H</td> </tr> <tr> <td><a href="#">MSP430F552x</a>, <a href="#">MSP430F551x</a></td> <td>SLAS590M</td> <td>SLAS590N</td> </tr> </tbody> </table> <p>These changes may be reviewed at the datasheet links provided.  <a href="http://www.ti.com/product/MSP430F5229">http://www.ti.com/product/MSP430F5229</a>  <a href="http://www.ti.com/product/MSP430F5513IRGCR">http://www.ti.com/product/MSP430F5513IRGCR</a></p>		Device Family	Change From:	Change To:	<a href="#">MSP430F522x</a> , <a href="#">MSP430F521x</a>	SLAS718G	SLAS718H	<a href="#">MSP430F552x</a> , <a href="#">MSP430F551x</a>	SLAS590M	SLAS590N
Device Family	Change From:	Change To:								
<a href="#">MSP430F522x</a> , <a href="#">MSP430F521x</a>	SLAS718G	SLAS718H								
<a href="#">MSP430F552x</a> , <a href="#">MSP430F551x</a>	SLAS590M	SLAS590N								

<b>Reason for Change:</b>			
The Datasheet for selected devices will be aligned with actual performance. The PMM BORH, COMP_B tEN, and DSBGA dimension will be changed, in addition to other editorial changes.			
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
<b>Changes to product identification resulting from this PCN:</b>			
None.			
<b>Product Affected:</b>			
MSP430F5227IYFFR	MSP430F5229IYFFR	MSP430F5229IYFFT	MSP430F5524IYFFR
MSP430F5526IYFFR	MSP430F5528IYFFR	MSP430F5528IYFFT	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
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Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>